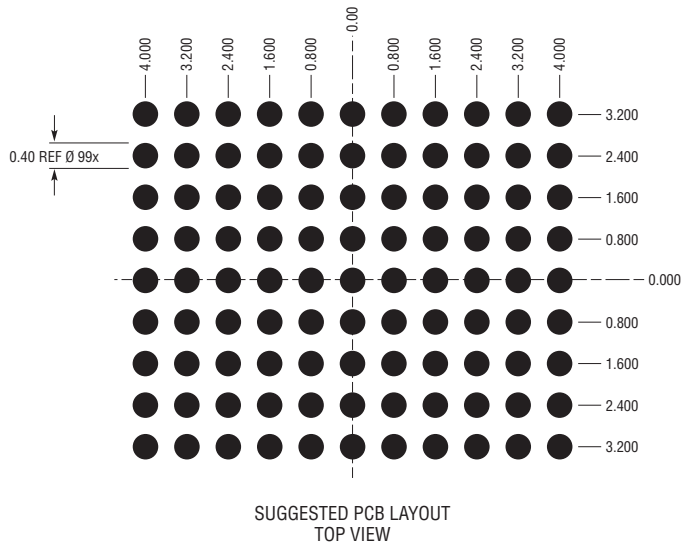
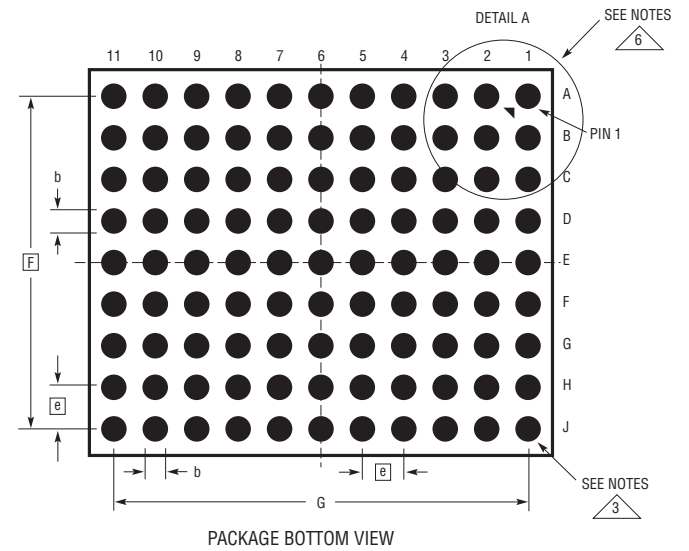
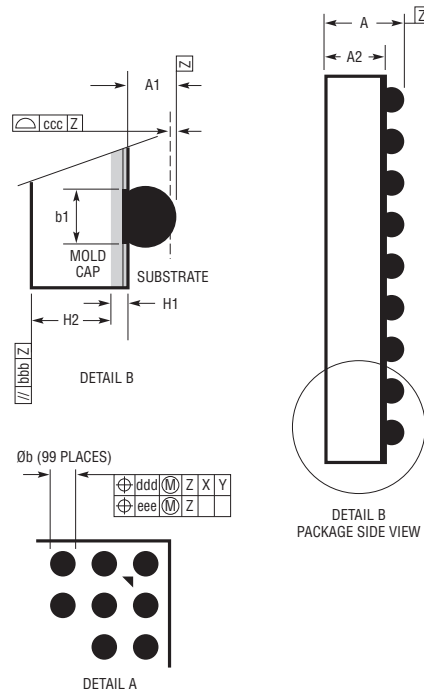
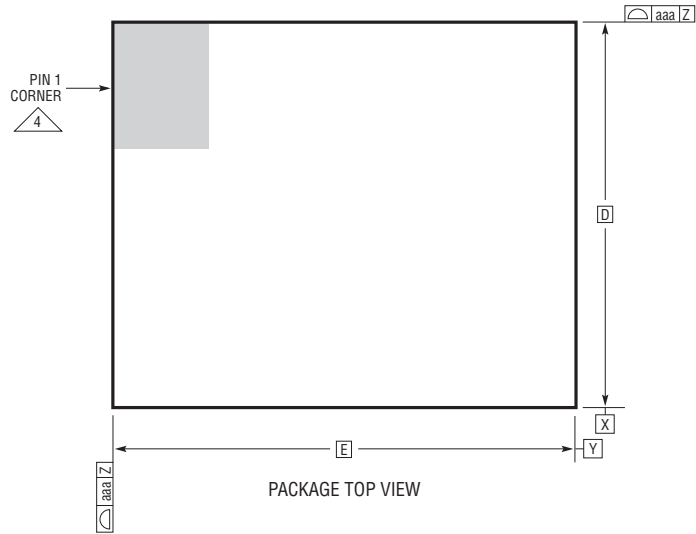


BGA Package
99-Lead (9mm × 7.5mm × 1.52mm)
 (Reference LTC DWG # 05-08-7029 Rev 0)



DIMENSIONS				
SYMBOL	MIN	NOM	MAX	NOTES
A	1.32	1.52	1.72	
A1	0.30	0.40	0.50	BALL HT
A2	1.02	1.12	1.22	
b	0.45	0.50	0.55	BALL DIMENSION
b1	0.37	0.40	0.43	PAD DIMENSION
D	7.50			
E	9.00			
e	0.80			
F	6.40			
G	8.00			
H1	0.32 REF			SUBSTRATE THK
H2	0.80 REF			MOLD CAP HT
aaa			0.15	
bbb			0.10	
ccc			0.20	
ddd			0.15	
eee			0.08	

TOTAL NUMBER OF BALLS: 99

- NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994
 2. ALL DIMENSIONS ARE IN MILLIMETERS. DRAWING NOT TO SCALE
 - 3 BALL DESIGNATION PER JEP95
 - 4 DETAILS OF PIN 1 IDENTIFIER ARE OPTIONAL, BUT MUST BE LOCATED WITHIN THE ZONE INDICATED. THE PIN 1 IDENTIFIER MAY BE EITHER A MOLD OR MARKED FEATURE
 5. PRIMARY DATUM -Z- IS SEATING PLANE

6 PACKAGE ROW AND COLUMN LABELING MAY VARY AMONG µModule PRODUCTS. REVIEW EACH PACKAGE LAYOUT CAREFULLY

